

(2)

L4 ANSWER 1 OF 1 WPIX (C) 2002 THOMSON DERWENT  
AN \*\*\*1998-476912\*\*\* [41] WPIX

DNC C1998-144127

TI Highly thermal conductive resin compsn. used as sealant and adhesive for electronic parts - comprises aluminium nitride powder treated with fluidity modifier and resin.

DC A28 A85 L03

PA (MITC) MITSUI PETROCHEM IND CO LTD

CYC 1

PI JP 10204300 A 19980804 (199841)\* 7p C08L101-00

ADT JP 10204300 A JP 1997-11493 19970124

PRAI JP 1997-11493 19970124

IC ICM C08L101-00

ICS C08K003-22; C08K003-28; C08K003-36; C08K009-02; C08K009-04

AB JP 10204300 A UPAB: 19981014

Resin compsn. (I) with high thermal conductivity comprises: 100 pts.wt. (A) resin(s); and 50-300 pts. wt. (B) aluminium nitride powder treated with fluidity modifier to improve fluidity. Resin compsn. with high thermal conductivity comprises: 100 pts.wt. (A) and 50-300 pts.wt. (C) waterproof aluminium nitride powder treated with fluidity modifier to improve fluidity is also claimed.

RCN

USE - (I) and (II) are useful as material for preparation of sealant and adhesive for electronic parts or material of laminate substrate(s), packaging material, etc.

ADVANTAGE - (I) and (II) have uniform compsn. and good thermal conductivity.

Dwg.0/0

FS CPI

FA AB

MC CPI: A08-M09A; A09-A03; L03-H04E1; L04-C20A

DRN 1694-U